

TRADEMARK ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT		
NATURE OF CONVEYANCE:	SECURITY INTEREST		
CONVEYING PARTY DATA			
Name	Formerly	Execution Date	Entity Type
Nitronex Corporation		11/03/2005	CORPORATION: DELAWARE
RECEIVING PARTY DATA			
Name:	Silicon Valley Bank		
Street Address:	3003 Tasman Drive		
City:	Santa Clara		
State/Country:	CALIFORNIA		
Postal Code:	95054-1191		
Entity Type:	CORPORATION: CALIFORNIA		
PROPERTY NUMBERS Total: 6			
Property Type	Number	Word Mark	
Serial Number:	75833680	NITRONEX	
Serial Number:	75844687	PENDEO	
Serial Number:	76171912	NITRONEX	
Serial Number:	76211705	SIGANTIC	
Registration Number:	2949681	N	
Serial Number:	78524159	SIGANTIC	
CORRESPONDENCE DATA			
Fax Number:	(404)962-6771		
	<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>		
Phone:	4048853539		
Email:	trademarks@troutmansanders.com		
Correspondent Name:	Segeda T. Ranjeet		
Address Line 1:	600 Peachtree Street NE		
Address Line 2:	Troutman Sanders LLP - Suite 5200		
Address Line 4:	Atlanta, GEORGIA 30308-2216		

OP \$165.00 75833680

ATTORNEY DOCKET NUMBER:	220763.571
NAME OF SUBMITTER:	Segeda T. Ranjeet
Signature:	/STR/
Date:	11/03/2005

Total Attachments: 9

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INTELLECTUAL PROPERTY SECURITY AGREEMENT

This Intellectual Property Security Agreement is entered into as of November 3 2005 by and between SILICON VALLEY BANK ("Bank") and NITRONEX CORPORATION ("Grantor").

RECITALS

A. Bank has agreed to make certain advances of money and to extend certain financial accommodation to Grantor (the "Loans") in the amounts and manner set forth in that certain Loan and Security Agreement by and between Bank and Grantor of even date herewith (as the same may be amended, modified or supplemented from time to time, the "Loan Agreement"; capitalized terms used herein are used as defined in the Loan Agreement). Bank is willing to make the Loans to Grantor, but only upon the condition, among others, that Grantor shall grant to Bank a security interest in certain Copyrights, Trademarks and Patents to secure the obligations of Grantor under the Loan Agreement.

B. Pursuant to the terms of the Loan Agreement, Grantor has granted to Bank a security interest in all of Grantor's right, title and interest, whether presently existing or hereafter acquired, in, to and under all of the Collateral.

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, and intending to be legally bound, as collateral security for the prompt and complete payment when due of its obligations under the Loan Agreement, Grantor hereby represents, warrants, covenants and agrees as follows:

AGREEMENT

To secure its obligations under the Loan Agreement, Grantor grants and pledges to Bank a security interest in all of Grantor's right, title and interest in, to and under its Intellectual Property Collateral (including without limitation those Copyrights, Patents and Trademarks listed on Schedules A, B and C hereto), and including without limitation all proceeds thereof (such as, by way of example but not by way of limitation, license royalties and proceeds of infringement suits), the right to sue for past, present and future infringements, all rights corresponding thereto throughout the world and all re-issues, divisions continuations, renewals, extensions and continuations-in-part thereof.

This security interest is granted in conjunction with the security interest granted to Bank under the Loan Agreement. The rights and remedies of Bank with respect to the security interest granted hereby are in addition to those set forth in the Loan Agreement and the other Loan Documents, and those which are now or hereafter available to Bank as a matter of law or equity. Each right, power and remedy of Bank provided for herein or in the Loan Agreement or any of the Loan Documents, or now or hereafter existing at law or in equity shall be cumulative and concurrent and shall be in addition to every right, power or remedy provided for herein and the exercise by Bank of any one or more of the rights, powers or remedies provided for in this Intellectual Property Security Agreement, the Loan Agreement or any of the other Loan Documents, or now or hereafter existing at law or in equity, shall not preclude the simultaneous or later exercise by any person, including Bank, of any or all other rights, powers or remedies.

IN WITNESS WHEREOF, the parties have caused this Intellectual Property Security Agreement to be duly executed by its officers thereunto duly authorized as of the first date written above.

Address of Grantor:

626 Hutton Street, Suite 106
Raleigh, NC 27606

Attn: Chief Executive Officer

Address of Bank:

3003 Tasman Drive
Santa Clara, CA 95054-1191

Attn: _____

GRANTOR:

NITRONEX CORPORATION

By: Cliff E. Kelly

Title: EXEC CHAIRMAN + CEO

BANK:

SILICON VALLEY BANK

By: _____

Title: _____

IN WITNESS WHEREOF, the parties have caused this Intellectual Property Security Agreement to be duly executed by its officers thereunto duly authorized as of the first date written above.

GRANTOR:

NITRONEX CORPORATION

Address of Grantor:

Attn: _____

By: _____

Title: _____

BANK:

SILICON VALLEY BANK

Address of Bank:

3003 Tasman Drive
Santa Clara, CA 95054-1191

Attn: _____

By: 

Title: DEAL TEAM LEADER

NITRONEX CORPORATION

EXHIBIT A

Copyrights

<u>Description</u>		<u>Registration/ Application Number</u>	<u>Registration/ Application Date</u>
N/A		N/A	N/A

EXHIBIT B

Patents

1. U.S. **Patent** No. 6,649,287, issued November 18, 2003 from U.S. Patent Application Serial No. 09/736,972, filed December 14, 2000, entitled "Gallium Nitride Materials and Methods"
2. U.S. **Patent** No. 6,617,060, issued September 9, 2003 from U.S. Patent Application Serial No. 10/188,814, filed July 02, 2002, entitled "Gallium Nitride Materials and Methods" which is a continuation of U.S. Patent Application Serial No. 09/736,972, filed December 14, 2000
3. U.S. Patent **Application** Serial No. 10/675,798, filed September 30, 2003, entitled "Gallium Nitride Materials and Methods" which is a continuation of U.S. Patent Application Serial No. 09/736,972, filed December 14, 2000
4. European **Application** Serial No. 01991120.5, filed December 14, 2001, entitled "Gallium Nitride Materials and Methods", a national of PCT Application Serial No. PCT/US01/48426, claiming priority to U.S. Patent Application Serial No. 09/736,972, filed December 14, 2000
5. Japanese **Application** Serial No. 2002-550144, filed December 14, 2001, entitled "Gallium Nitride Materials and Methods", a national of PCT Application Serial No. PCT/US01/48426, claiming priority to U.S. Patent Application Serial No. 09/736,972, filed December 14, 2000
6. Taiwanese Application Serial No. 90130606, filed December 11, 2001, entitled "Gallium Nitride Materials and Methods", claiming priority to U.S. Patent Application Serial No. 09/736,972, filed December 14, 2000
7. U.S. **Patent** No. 6,611,002, issued August 26, 2003 from U.S. Patent Application Serial No. 09/792,414, filed February 23, 2001, entitled "Gallium Nitride Material Devices and Methods Including Backside Vias"
8. European Patent **Application** Serial No. 02721099.6, filed February 23, 2002, entitled "Gallium Nitride Material Devices and Methods Including Backside Vias", a national of PCT Application Serial No. PCT/US02/05182, claiming priority to U.S. Patent Application Serial No. 09/792,414, February 23, 2001
9. Japanese Patent **Application** Serial No. TBA, filed February 23, 2002, entitled "Gallium Nitride Material Devices and Methods Including Backside Vias", a national of PCT Application Serial No. PCT/US02/05182, claiming priority to U.S. Patent Application Serial No. 09/792,414, February 23, 2001
10. Taiwanese **Patent** No. 178213, filed December 11, 2001, entitled "Gallium Nitride Material Devices and Methods Including Backside Vias" claiming priority to U.S. Patent Application Serial No. 09/792,414, February 23, 2001
11. U.S. Patent **Application** Serial No. 10/650,122, filed August 25, 2003, entitled "Gallium Nitride Material Devices and Methods Including Backside Vias" which is a continuation-in-part of U.S. Patent Application 09/792,414, filed February 23, 2001
12. International Patent **Application** Serial No. PCT/US2004/027657, filed August 25, 2004, entitled "Gallium Nitride Material Devices and Methods Associated With the Same" claiming priority to U.S. Patent Application Serial No. 10/650,122, filed August 25, 2003

13. U.S. **Patent** No. 6,956,250, issued October 18, 2005 from U.S. Patent Application Serial No. 09/792,409, filed February 23, 2001, entitled "Gallium Nitride Materials Including Thermally Conductive Regions"
14. U.S. Patent **Application** Serial No. 11/050,598, filed February 3, 2005, entitled "Gallium Nitride Materials Including Thermally Conductive Regions", which is a continuation of U.S. Patent **Application** Serial No. 09/792,409, filed February 23, 2001
15. European Patent **Application** Serial No. 02790164.6, filed February 23, 2002, entitled "Gallium Nitride Materials Including Thermally Conductive Regions", a national of PCT Application Serial No. PCT/US02/05460, claiming priority to U.S. Patent Application Serial No. 09/792,409, February 23, 2001
16. Japanese Patent **Application** Serial No. 2002-568402, filed February 23, 2002, entitled "Gallium Nitride Materials Including Thermally Conductive Regions", a national of PCT Application Serial No. PCT/US02/05460, claiming priority to U.S. Patent Application Serial No. 09/792,409, February 23, 2001
17. Taiwanese **Patent** No. 178128, filed February 23, 2002, entitled "Gallium Nitride Materials Including Thermally Conductive Regions" claiming priority to U.S. Patent Application Serial No. 09/792,409, February 23, 2001
18. U.S. Patent **Application** Serial No. 10/047,455, filed January 15, 2001, entitled "Semiconductor Structures Including A Gallium Nitride Material Component And A Silicon Germanium Component"
19. U.S. Patent **Application** Serial No. 10/913,297, filed August 5, 2004, entitled "Gallium Nitride Material Transistors and Methods Associated With the Same" claiming priority to U.S. Provisional Patent Application Serial No. 60/493,039, filed August 5, 2003
20. International Patent **Application** Serial No. PCT/US2004/025433, filed August 5, 2004, entitled "Gallium Nitride Material Transistors and Methods Associated With the Same" claiming priority to U.S. Provisional Patent Application Serial No. 60/493,039, filed August 5, 2003
21. U.S. Patent **Application** Serial No. 10/740,376, filed December 17, 2003, entitled "Gallium Nitride Material Devices Including an Electrode-Defining Layer and Methods of Forming The Same"
22. International Patent **Application** Serial No. PCT/US2004/042260, filed December 16, 2004, entitled "Gallium Nitride Material Devices Including an Electrode-Defining Layer and Methods of Forming The Same" claiming priority to U.S. Patent Application Serial No. 10/740,376, filed December 17, 2003
23. U.S. Patent **Application** Serial No. 10/879,704, filed June 28, 2004, entitled "Semiconductor Device-Based Sensors and Methods Associated With the Same"
24. International Patent **Application** Serial No. NYA, filed June 24, 2005, entitled "Semiconductor Device-Based Sensors and Methods Associated With the Same" claiming priority to U.S. Patent Application Serial No. 10/879,704, filed June 28, 2004
25. U.S. Patent **Application** Serial No. 10/879,703, filed June 28, 2004, entitled "Gallium Nitride Materials and Methods Associated With the Same"
26. International Patent **Application** Serial No. US 2005/022488, filed June 24, 2005, entitled "Gallium Nitride Materials and Methods Associated With the Same" claiming priority to U.S. Patent Application Serial No. 10/879,703, filed June 28, 2004

27. U.S. Patent **Application** Serial No. 10/879,795, filed June 28, 2004, entitled "Gallium Nitride Material Structures Including Isolation Regions and Methods"
28. International Patent **Application** Serial No. US 2005/022470, filed June 24, 2005, entitled "Gallium Nitride Material Structures Including Isolation Regions and Methods" claiming priority to U.S. Patent Application Serial No. 10/879,795, filed June 28, 2004
29. U.S. Patent **Application** Serial No. 10/886,506, filed July 7, 2004, entitled "III-Nitride Materials Including Low Dislocation Densities and Methods Associated With the Same"
30. International Patent **Application** Serial No. US 2005/023934, filed July 6, 2005, entitled "III-Nitride Materials Including Low Dislocation Densities and Methods Associated with the Same"
31. U.S. Patent **Application** Serial No. 60/622,871, filed October 28, 2004, entitled "Monolithic Microwave Integrated Circuits"
32. U.S. Patent **Application** Serial No. 11/004,628, filed December 3, 2004, entitled "III-Nitride Material Structures Including Silicon Substrates"
33. U.S. Patent **Application** Serial No. 11/096,505, filed April 1, 2005, entitled "Gallium Nitride Materials and Methods Associated With the Same"
34. U.S. Patent **Application** Serial No. 11/121,793, filed May 3, 2005, entitled "Gallium Nitride Material Structures Including Substrates and Methods Associated With the Same"
35. U.S. Patent **Application** Serial No. 60/723,824, filed October 4, 2005, entitled "Gallium Nitride Material Transistors and Methods for Wideband Applications"

At this time Grantor has several other Invention and Trade Secret disclosures on file with Grantor's IP counsel, Wolf, Greenfield & Sacks,

Grantor is party to the following license agreements regarding Grantor's intellectual property rights.

1. Sublicense Agreement by and between Grantor and Sony Corporation, effective as of April 10, 2001
2. License Agreement by and between Grantor and International Rectifier Corporation, dated December 31, 2004

EXHIBIT C

Trademarks

1. Mark – Nitronex Corporation; Filing Date – March 11, 1999; U.S.; Int. Class – 9; Serial Number – 75/658,492 – instructions received to abandon 4/11/03
2. Mark – Nitronex; Filing Date -- October 28, 1999; U.S.; Int. Class – 9; Serial Number – 75/833,680 – allowed
3. Mark – Pendeo; Filing Date – November 9, 1999; U.S.; Int. Class – 9, 40; Serial Number – 75/844,687 – opposition proceeding
4. Mark - Pendeoepitaxy; Filing Date – November 9, 1999; U.S.; Int. Class – 9, 040; Serial Number – 75/845,791 – allowed
5. Mark – Nitronex; Registered – December 22, 2000; Japan; Class – 9; Registration Number – 4441756
6. Mark – Nitronex; Registered – December 20, 2001; Korea; Class – 9; Registration No. - 0509135
7. Mark -- Nitronex; Registered – April 28, 2000; European Community; Registration Number - 1633601
8. Mark – Nitronex; Registered - August 16, 2001; Taiwan; Class – 9; Registration Number - 954582
9. Mark – Pendeo; Registered – November 9, 1999; Singapore; Class – 9; Registration No. – T00/07633H
10. Mark – Pendeo; Registered – August 11, 2001; Taiwan; Class – 9; Registration No. 954618
11. Mark -- Pendeo; Registered - July 16, 2001; Taiwan; Class – 40; Registration Number - 145848
12. Mark – Pendeo; Registered – October 5, 2001; Japan; Class – 9, 40; Registration Number - 4511730
13. Mark – Pendeo; Registered – May 8, 2000; European Community; Registration No. – 1643972
14. Mark – Pendeo; Registered - January 24, 2002 –; Korea; Class – 9; Registration Number - 0004585
15. Mark – Pendeo; Filing Date – March 13, 2001; Australia; Class – 9, 40; Serial Number 869246
16. Mark – Pendeo; Filing Date – October 14, 2002; China; Class – 40; Serial Number - 2001078177
17. Mark – Pendeo; Registered - March 14, 2001; Hong Kong; Class – 9; Registration No. – 12378/2001
18. Mark – Pendeo; Registered – March 14, 2001; Hong Kong; Class – 40; Registration No. – 12379/2001
19. Mark – Pendeo; Registered – May 25, 2001; Indonesia; Class – 9; Registration No. - 503314
20. Mark – Pendeo; Filing Date -- April 9, 2001; Malaysia; Class – 9; Serial Number 2001/04436
21. Mark – Pendeo; Filing Date – April 9, 2001; Malaysia; Class – 40; Serial Number 2001/04435
22. Mark – Pendeo; Registered – September 9, 2002; New Zealand; Class – 9; Registration No. - 633996
23. Mark – Pendeo; Registered – September 9, 2002; New Zealand; Class – 40; Registration No. - 633997

24. Mark -- Pendeo; Filing Date -- March 16, 2001; Philippines; Class -- 9, 40; Serial Number - 0001936
25. Mark -- Pendeo; Registered -- April 5, 2001; Thailand; Class -- 9; Registration No. -- TM154442
26. Mark -- Pendeo; Registered -- July 4, 2002; Vietnam; Class -- 9, 40; Registration No. - 41884
27. Mark -- Pendeo; Registered -- November 9, 2999; Singapore; Class --40; Registration No. -- T00/07634F
28. Mark -- Nitronex; Filing Date -- November 28, 2000; U.S.; Int. Class -- 9, 42; Serial Number 76/171,912
29. Mark -- Sigantic; Filing Date -- February 16, 2001; U.S.; Int. Class -- 9; Serial Number --76/211,705
30. Mark -- Sigantic; Filing Date -- February 16, 2001; U.S.; Int. Class -- 40; Serial Number --76/211,995
31. Mark -- Pendeo; Registered -- November 18, 2002; Korea; Class -- 40; Registration No. -- 81435
32. Mark -- Sigantic; Registered -- July 27, 2001; Australia; Class -- 9; Registration No. -- 883999
33. Mark -- Sigantic; Registered -- November 28, 2002; China; Class -- 9; Registration No. -- 1983060
34. Mark -- Sigantic; Registered -- October 23, 2002; Hong Kong; Class -- 9; Registration No. 13742/2002
35. Mark - Sigantic; Filing Date -- August 16, 2001; Indonesia; Class -- 9; Serial Number --
D002001.17871.17989
36. Mark -- Sigantic; Filing Date -- August 8, 2001; Philippines; Class -- 9; Serial Number -- 4-2001-0005787
37. Mark - Sigantic; Filing Date -- August 2, 2001; Singapore; Class -- 9; Serial Number -- T01/12010A
38. Mark -- Sigantic; Filing Date -- August 16, 2001; Thailand; Class -- 9; Serial Number 462836
39. Mark -- Sigantic; Filing Date -- August 10, 2001; Malaysia; Class -- 9; Serial Number -- 2001/10395
40. Mark -- N logo; Registered -- May 10, 2005; U.S.; Class -- 1, 9, 40, 42; Registration Number -- 2949681
41. Mark -- Sigantic; Registered - February 16, 2001; New Zealand; Class - 9; Registration Number 642405
42. Mark -- Pendeo; Registered -- April 21, 2002; China; Class -- 9; Registration Number -- 1752888
43. Mark -- Pendeo; Registered -- May 20, 2002; Indonesia; Class - 40; Registration Number -- 508506
44. Mark -- Pendeo; Registered -- June 26, 2002; Thailand; Class -- 40; Registration Number -- SM16439
45. Mark -- Sigantic; Registered - September 27, 2002; European Community; Class - 9; Registration Number
-- 2320612
46. Mark -- Sigantic -- Registered -- March 20, 2003; Japan; Class -- 9; Registration Number -- 4654922
47. Mark -- Sigantic -- Registered -- December 16, 2002; Taiwan; Class -- 9; Registration Number -- 1026312
48. Mark -- Sigantic -- Registered -- May 23, 2003; Korea; Class -- 9; Registration Number - 40-548977
49. Mark -- Sigantic -- Registered -- January 13, 2003; Vietnam; Class - 9; Registration Number -- 44806
50. Mark -- Sigantic -- Filing Date -- November 30, 2004; U.S.; Class -- 9; Serial Number -- 78/524159